



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



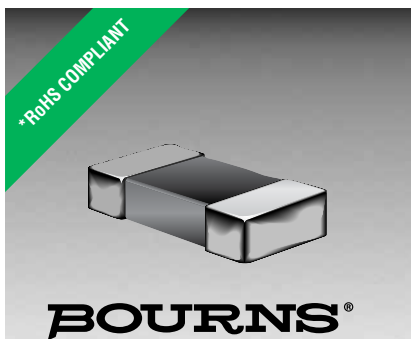
Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Features

- Monolithic construction offering high reliability
- Magnetically shielded construction providing low radiation
- Low DC resistance
- Low profile, 1008 size (2.5 x 2 x 0.9 mm)
- RoHS compliant*

Applications

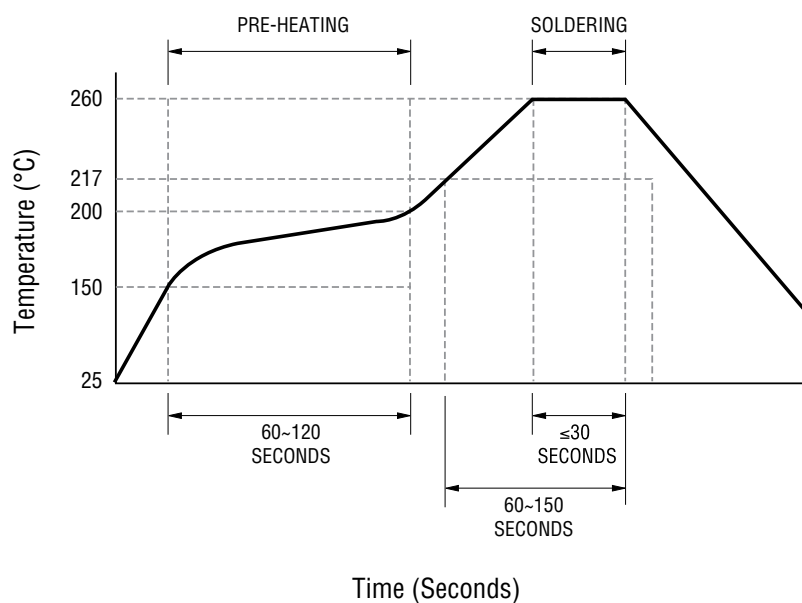
- DC/DC converters for:
 - Smart phones
 - DVCs / DSCs
 - Tablets
 - HDDs / SSDs
 - Mobile electronic devices

CVH252009 Series Multilayer Power Chip Inductors

Electrical Specifications

Bourns® Part No.	Inductance @ 1 MHz		SRF (MHz)	DCR (Ohms)	IDC (mA)
	L (μH)	Tol.	Typ.	Max.	
CVH252009-R47M	0.47	±20 %	100	0.04	1800
CVH252009-1R0M	1.0	±20 %	60	0.055	1600
CVH252009-1R5M	1.5	±20 %	50	0.07	1500
CVH252009-2R2M	2.2	±20 %	40	0.08	1300
CVH252009-3R3M	3.3	±20 %	30	0.10	1200
CVH252009-4R7M	4.7	±20 %	25	0.11	1100

Soldering Profile (Lead Free Solder)



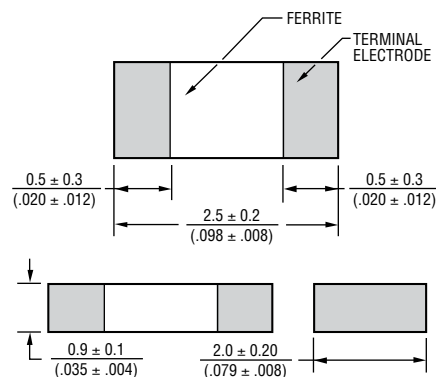
General Specifications

Operating Temperature
-55 °C to +125 °C
 (Temperature rise included)
 Storage Temperature
+40 °C max. at 70 % RH
 Resistance to Soldering Heat
+260 °C
 Temperature Rise
 40 °C at rated current

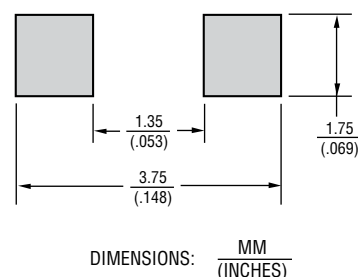
Materials

Core.....Ferrite
 Terminal.....Ni/Sn
 Packaging..... 3000 pcs. per 7 inch reel

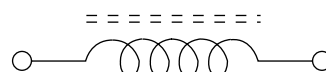
Product Dimensions



Recommended Layout



Schematic



BOURNS®

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 EMEA: Tel: +36 88 520 390 • Fax: +36 88 520 211
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www.bourns.com

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

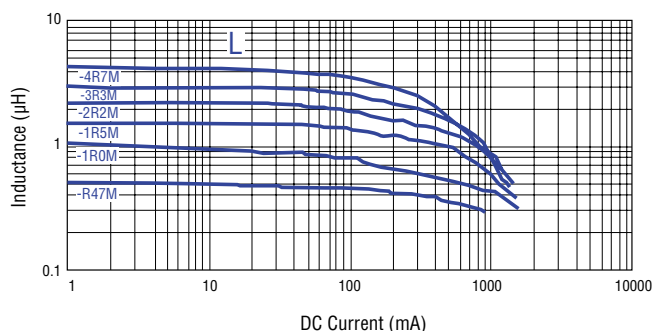
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

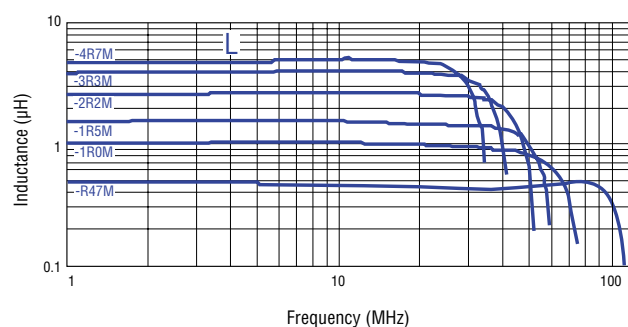
CVH252009 Series Multilayer Power Chip Inductors

BOURNS®

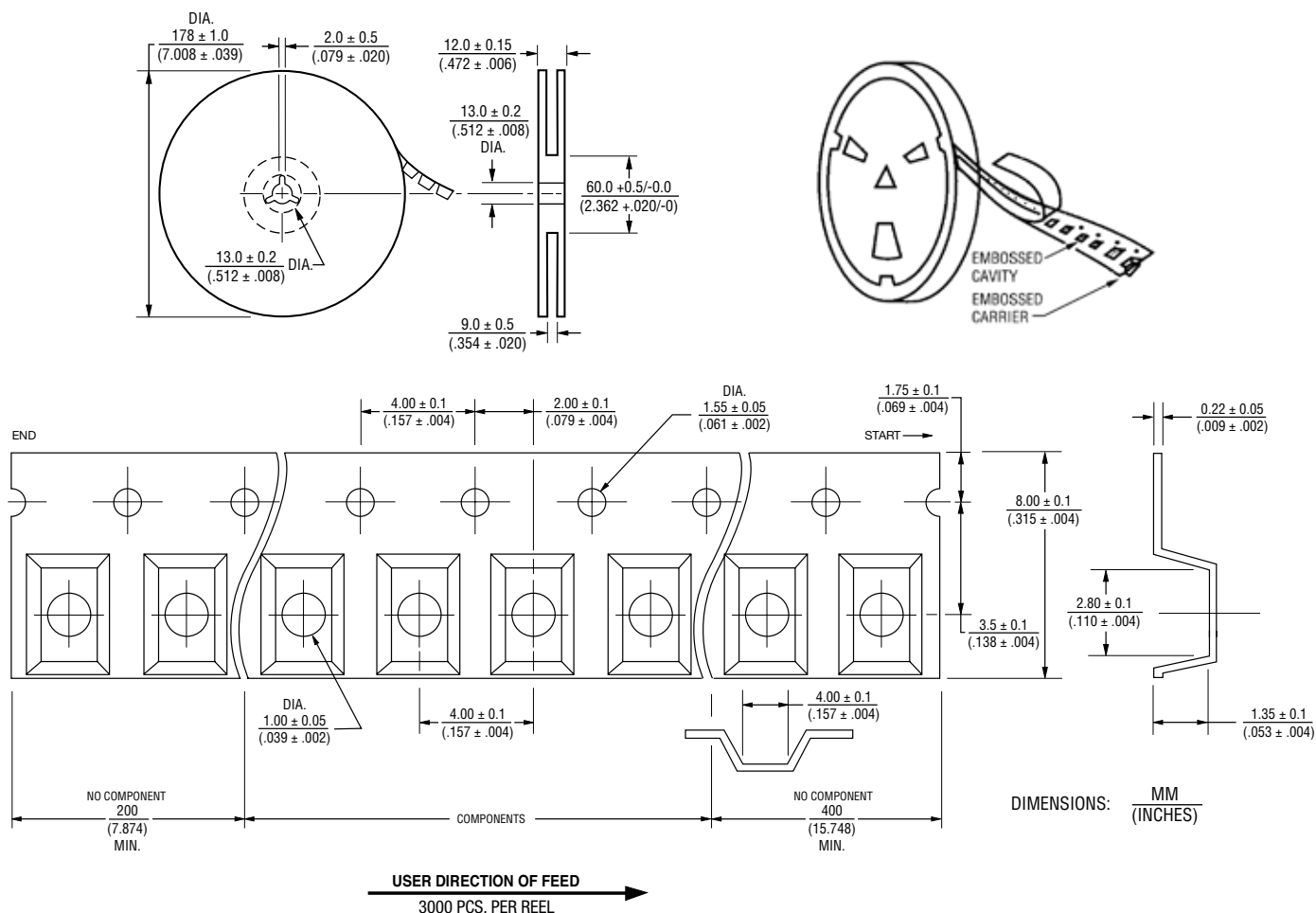
L vs. Idc



L vs. Frequency



Packaging Specifications



REV. 04/16

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